Bluetooth Module Datasheet

CZW-5126-02

Model:CZW-5126-02

Hardware Version: V2.0

Release Date: 2019.03.16

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Shenzhen

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1 summary

CZW-5126-02 is a Bluetooth module designed by ShenZhen Cheng Zhi Wei Technology Co.,Ltd. using Qualcomm Bluetooth chip qcc5126。

CZW-5126-02 is a Bluetooth, audio and programmable application processor. It includes high-performance, analog, and digital audio codecs, Class-AB and Class-D headphone drivers, advanced power management, Li-ion battery charger, light-emitting diode (LED) drivers, and flexible interfaces including inter₁ integrated circuit sound (I²S), universal asynchronous receiver transmitter(UART), and programmable input/output (PIO)_o

CZW-5126-02 package is compatible with czw02 series pins, easy replacement and upgrade

2 General specifications

Model Name	CZW-5126-02
Package	54 Pin Module
Dimension	13mm x 18mm x 2.4mm
Chipset	QCC5126
Bluetooth Version	Bluetooth 5.1
Power Class	Class2
Transmission Distance	≥10M
Voltage	2.8~4.2V
Temperature	-10∼+70℃
Storage Temperature	-40∼+85℃
Frequency Range	2402~2480MHz
Maximum RF Transmit Power	9dBm
π/4 DQPSK Receive Sensitivity	-96dBm
8DPSK Receive Sensitivity	-89dBm

3 Key Features

3.1 Audio subsystem

- ★ Dual 32bit Kalimba audio digital signal processor (DSP) cores with flexible clocking from 2 MHz to 120 MHz to allow optimization and trade-off performance vs. Power consumption
- ★ DSPs execute code from ROM and from program RAM, original equipment manufacturer (OEM) and third party developed features can run from program RAM
- ★ 80 KB program RAM
- ★ 256 KB data RAM
- ★ 5 Mb ROM
- ★ 16 Mb Audio buffer RAM

3.2 Application subsystem

- ★ Dual core application subsystem 32/80 MHz operation
- ★ 32- bit Firmware Processor:
- ★ 32- bit Developer Processor:
- ★ Both cores execute code from external flash memory using QSPI clocked at 32 MHz or 80 MHz
- ★ On-chip caches per core allow for optimized performance and power consumption Bluetooth subsystem
- ★ Qualified to Bluetooth v5.0 specification including 2 Mbps Bluetooth low energy (Production parts)
- ★ Single ended antenna connection with on-chip balun and Tx/Rx switch
- ★ Bluetooth, Bluetooth low energy, and mixed topologies supported
- ★ Class 1 support

3.3 Li-ion battery charger

- ★ Integrated battery charger supporting internal mode (up to 200 mA) and external mode (up to 1.8 A)
- ★ Variable float (or termination) voltage adjustable in 50 mV steps from 3.65 V to 4.4 V
- ★ Thermal monitoring and management are implementable in application sftware
- ★ Pre-charge to fast charge transition configurable at 2.5 V, 2.9 V, 3.0 V, and 3.1 V Power management
- ★ Integrated power management unit (PMU) to minimize external components
- ★ QCC5126 VFBGA runs directly from a Li-ion, USB, or external supply (2.8 V to 6.5 V)
- ★ Auto-switching between battery and USB (or other) charging source
- ★ Power islands employed to optimize power consumption for variety of use-cases
- ★ Dual switch-mode power supply (SMPS)

3.4 Audio engine and digital audio interfaces

- ★ 24-bit I²S interface with 1 input and 3 output channels
- ★ Programmable audio master clock (MCLK)
- ★ Sony/Philips digital interface (SPDIF): 2, configurable as input or output
- ★ Stereo analog outputs configurable as differential Class-AB headphone outputs or differential high efficiency Class-D outputs:
- ★ Dual analog inputs configurable as single ended line inputs or, unbalanced or balanced analog microphone inputs:
- ★ 1 microphone bias (single bias shared by the two channels):
- ★ Digital microphone inputs with capability to interface up to 6 digital microphones
- ★ Both analog-to-digital converter (ADC)s and digital-to-analog converter (DAC)s support sample rates of 8, 16, 32, 44.1, 48, 96 kHz. DACs also support 192 kHz.

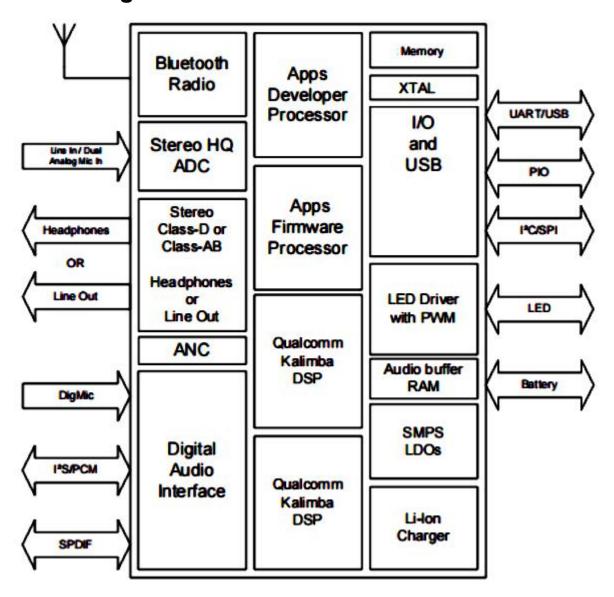
3.5 Peripherals and physical interfaces

- ★ A UART interface
- ★ 2 x Bit Serializers (programmable serial peripheral interface (SPI) and I²C hardware accelerator)
- ★ 1 x USB interface:
- ★ A secure digital input/output (SDIO) v2.0 compliant Host with 1 port, capable of interfacing to storage device (SD), or multimedia card (MMC) cards
- ★ QSPI NOR flash interface
- ★ Up to 19 PIO and 5 open drain/digital input LED pads with pulse width modulation (PWM)

4 Applications

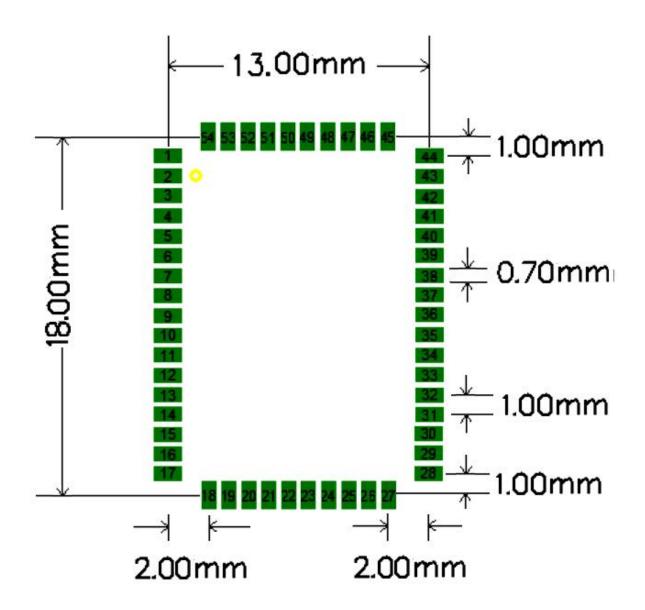
- ★ Wireless speakers
- ★ Wired/wireless stereo headsets/headphones
- ★ Qualcomm True Wireless[™] stereo earbuds/speakers

5 Block Diagram

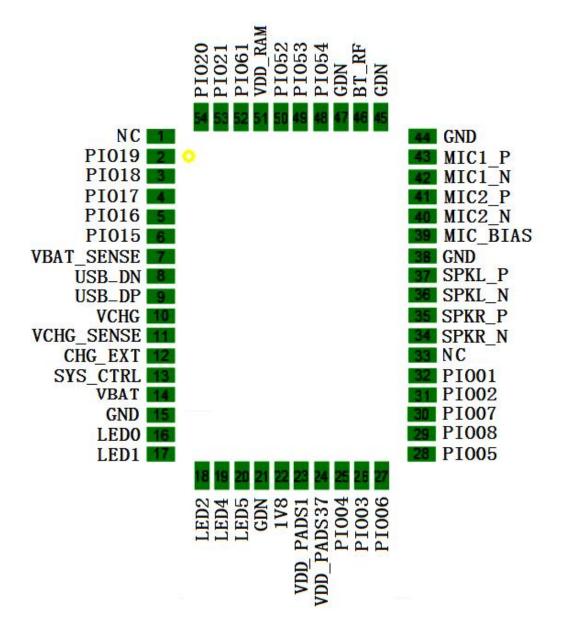


6 Module Package Information

6.1 Pinout Diagram and package dimensions



6.2 Module Pin descriptions



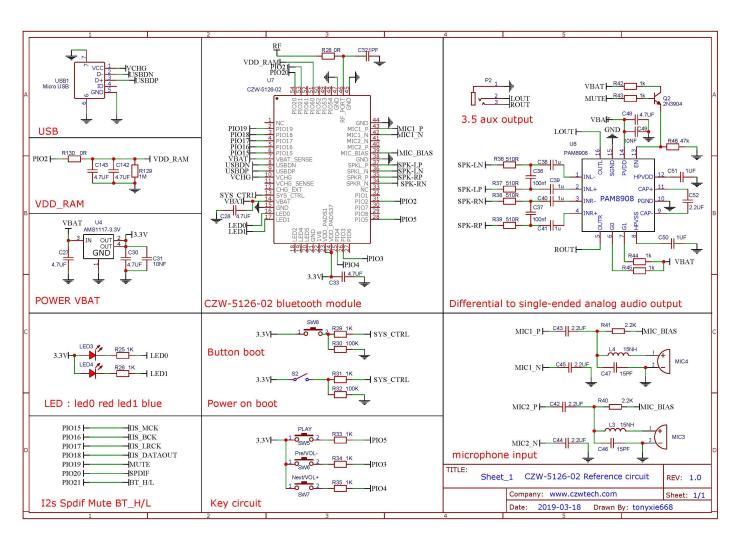
7 Pin Function Description

Pin#	Pin Name	Pin type	Description
1	NC	NC Digital: Bidirectional with	NC Programmable I/O line 19.
2	PIO[19]	programmable strength internal pull- up/pull-down	Alternative function: PCM_DIN[0]
		Digital: Bidirectional with	Programmable I/O line 18.
3	PIO[18]	programmable strength internal pull- up/pull-down	Alternative function: PCM_DOUT[0]
4	DIO[17]	Digital: Bidirectional with	Programmable I/O line 17.
	PIO[17]	programmable strength internal pull- up/pull-down	Alternative function: PCM_SYNC
5	PIO[16]	Digital: Bidirectional with programmable strength internal	Programmable I/O line 16.
	110[10]	pull- up/pull-down	Alternative function: PCM_CLK
6	PIO[15]	Digital: Bidirectional with programmable strength internal	Programmable I/O line 15.
		pull- up/pull-down	Alternative function: MCLK_OUT
7	VBAT_SENSE	Analog	Battery voltage sense input.
8	USB DN	Digital	USB Full Speed device D- I/O. IEC-61000-4-2 (device level) ESD Protection
	_		USB Full Speed device D+ I/O. IEC-61000-4-2
9	USB_DP	Digital	(device level) ESD Protection
10	VCHG	Supply	Charger input to Bypass regulator.
11	VCHG_SENSE	Analog	Charger input sense pin after external mode sense-resistor. High impedance.
			NOTE If using internal charger or no charger, connect VCHG_SENSE direct to VCHG.
12	CHG_EXT	Analog	External charger transistor current control. Connect to base of external charger transistor as per application schematic.
13	SYS_CTRL	Digital input	Typically connected to an ON/OFF push button. Boots device in response to a button press when power is still present from battery and/or charger but software has placed the device in the OFF or DORMANT state. Additionally useable as a digital input in normal operation. No pull. Additional function: PIO[0] input only
14	VBAT	Supply	Battery voltage input.
15	GND	Ground	Ground
		Analog or digital input/ open drain	General-purpose analog/digital input or open
16	LED[0]	output. Analog or digital input/ open drain	drain LED output. General-purpose analog/digital input or open
17	LED[1]	output.	drain LED output.

Pin#	Pin Name	Pin type	Description
18	LED[2]	Analog or digital input/open drain output.	General-purpose analog/digital input or open drain LED output.
19	LED[4]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.
20	LED[5]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.
21	GND	Ground	Ground
22	1V8	Supply	1.8V voltage output
23	VDD_PADS_1	Supply	1.8 V/3.3 V PIO supply.
24	VDD_PADS_3、7	Supply	1.8 V/3.3 V PIO supply.
25	PIO[4]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 4. Alternative function: TBR_MOSI[1]
26	PIO[3]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 3. Alternative function: TBR_MISO[2]
27	PIO[6]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 6. Alternative function: TBR_MOSI[0]
28	PIO[5]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 5. Alternative function: TBR_MISO[1]
29	PIO[8]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 8. Alternative function: TBR_CLK
30	PIO[7]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 7. Alternative function: TBR_MISO[0]
31	PIO[2]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 2. Alternative function: TBR_MISO[3]
32	PIO[1]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Automatically defaults to RESET# mode when the device is unpowered, or in off modes. Reconfigurable as a PIO after boot. Alternative function: Programmable I/O line 1
33	NC	NC	NC
34	SPKR_N	VDD_AUDIO_HP_ SPKR	Headphone/speaker differential right output, negative. Alternative function: Differential right line output, negative
35	SPKR_P	VDD_AUDIO_HP_ SPKR	Headphone/speaker differential right output, positive. Alternative function: Differential right line output, positive
36	SPKL_N	VDD_AUDIO_HP_ SPKL	Headphone/speaker differential left output, negative. Alternative function: Differential left line output, negative

Pin#	Pin Name	Pin type	Description	
37	SPKL_P	VDD_AUDIO_HP_ SPKL	Headphone/speaker differential left output, positive. Alternative function: Differential left line output, positive	
38	GND	Ground	Ground	
39	MIC_BIAS	VDD_AUDIO_1V8	Mic bias output.	
40	MIC2_N	VDD_AUDIO_1V8	Microphone differential 2 input, negative. Alternative function: Differential audio line input right, negative	
41	MIC2_P	VDD_AUDIO_1V8	Microphone differential 2 input, positive. Alternative function: Differential audio line input right, positive	
42	MIC1_N	VDD_AUDIO_1V8	Microphone differential 1 input, negative. Alternative function: Differential audio line input left, negative	
43	MIC1_P	VDD_AUDIO_1V8	Microphone differential 1 input, positive. Alternative function: Differential audio line input left, positive	
44	GND	Ground	Ground	
45	GND	Ground	Ground	
46	BT_RF	VDD_BT_RADIO	Bluetooth transmit/receive.	
47	GND	Ground	Ground	
48	PIO[54]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 54. Alternative function: SDIO_D[0]	
49	PIO[53]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 53. Alternative function: SDIO_CMD	
50	PIO[52]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 52. Alternative function: SDIO_CLK	
51	VDD_RAM	Supply	1.8 V PIO supply for Audio buffer RAM.	
52	PIO[61]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 61.	
53	PIO[21]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 21. Alternative function: PCM_DOUT[2]	
54	PIO[20]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 20. Alternative function: PCM_DOUT[1]	

8 Reference application circuit



Notice: for reference only, please design the circuit according to the actual application

9 Electrical Characteristics

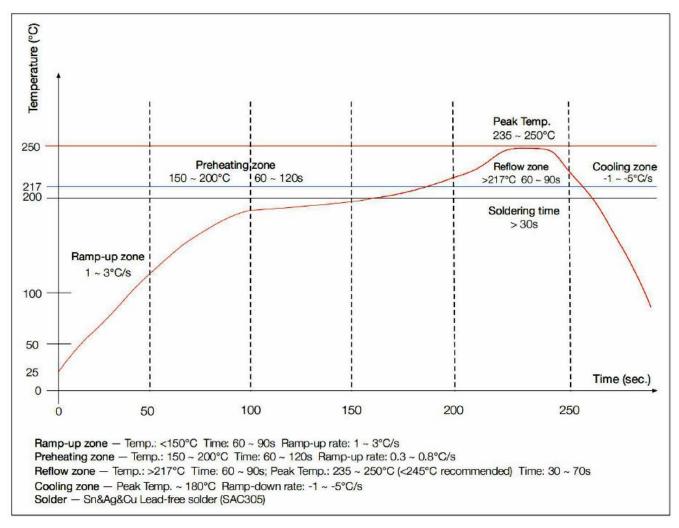
9.1 Absolute Maximum Ratings

Rating	Minimum	Maximum
Storage temperature	-40°C	+85℃

9.2 Recommended Operating Conditions

Operating Condition	Minimum	Maximum
Operating temperature range	-40°C	+85℃
Supply voltage: VBAT	+2.8V	+4.3V

10 Recommended reflow temperature profile



The module Must go through 100°C baking for at least 12 hours before SMT AND IR reflow process!

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